Kaimeite Electronic (HK) Co., Limited
First choice One-Stop Mixed Distributor for World-Class manufacturer Email: info@kaimte.com Website: www.kaimte.com

Click to view price, real time Inventory, Delivery & Lifecycle Information;

NRVB0540T1G

onsemi

Schottky Diodes & Rectifiers REC 0.5A 40V SHTY

Any questions, please feel free to contact us. info@kaimte.com

Surface Mount Schottky Power Rectifier

SOD-123 Power Surface Mount Package

The Schottky Power Rectifier employs the Schottky Barrier principle with a barrier metal that produces optimal forward voltage drop—reverse current tradeoff. Ideally suited for low voltage, high frequency rectification, or as a free wheeling and polarity protection diodes in surface mount applications where compact size and weight are critical to the system. This package provides an alternative to the leadless 34 MELF style package.

Features

- Guardring for Stress Protection
- Very Low Forward Voltage
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Package Designed for Optimal Automated Board Assembly
- AEC-Q101 Qualified and PPAP Capable
- NRVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- All Packages are Pb–Free*

Mechanical Characteristics

• Device Marking: B4

• Polarity Designator: Cathode Band

• Weight: 11.7 mg (approximately)

Case: Epoxy Molded

- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C max. for 10 Seconds
- ESD Rating:
 - ♦ Human Body Model = 3B
 - ♦ Machine Model = C



ON Semiconductor®

http://onsemi.com

SCHOTTKY BARRIER RECTIFIER 0.5 AMPERES, 40 VOLTS



SOD-123 CASE 425 STYLE 1

MARKING DIAGRAM



B4 = Device Code M = Date Code • = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
MBR0540T1G	SOD-123 (Pb-Free)	3,000/Tape & Reel (8 mm Tape, 7" Real)
NRVB0540T1G	SOD-123 (Pb-Free)	3,000/Tape & Reel (8 mm Tape, 7" Real)
MBR0540T3G	SOD-123 (Pb-Free)	10,000/Tape & Reel (8 mm Tape, 13" Real)
NRVB0540T3G	SOD-123 (Pb-Free)	10,000/Tape & Reel (8 mm Tape, 13" Real)

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	40	V	
Average Rectified Forward Current (At Rated V_R , $T_C = 115^{\circ}C$)	Io	0.5	А	
Peak Repetitive Forward Current (At Rated V _R , Square Wave, 20 kHz, T _C = 115°C)	I _{FRM}	1.0	Α	
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	5.5	А	
Storage/Operating Case Temperature Range	T _{stg} , T _C	-55 to +150	°C	
Operating Junction Temperature	TJ	-55 to +150	°C	
Voltage Rate of Change (Rated V_R , $T_J = 25$ °C)	dv/dt	1000	V/µs	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance – Junction–to–Lead (Note 1) Thermal Resistance – Junction–to–Ambient (Note 2)	R _{tjl} R _{tja}	118 206	°C/W

^{1.} Mounted with minimum recommended pad size, PC Board FR4.

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value		Unit
Maximum Instantaneous Forward Voltage (Note 3)	VF	T _J = 25°C	T _J = 100°C	V
$(i_F = 0.5 \text{ A})$ $(i_F = 1 \text{ A})$		0.51 0.62	0.46 0.61	
Maximum Instantaneous Reverse Current (Note 3)	I _R	T _J = 25°C	T _J = 100°C	μΑ
(V _R = 40 V) (V _R = 20 V)		20 10	13,000 5,000	

^{3.} Pulse Test: Pulse Width ≤ 250 µs, Duty Cycle ≤ 2.0%.

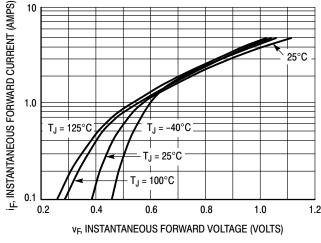


Figure 1. Typical Forward Voltage

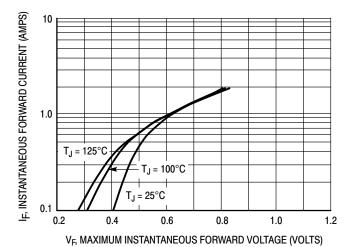


Figure 2. Maximum Forward Voltage

^{2. 1} inch square pad size (1 X 0.5 inch for each lead) on FR4 board.

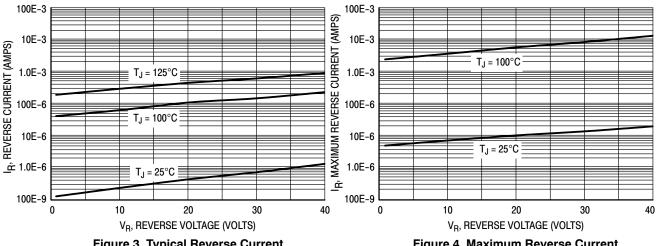
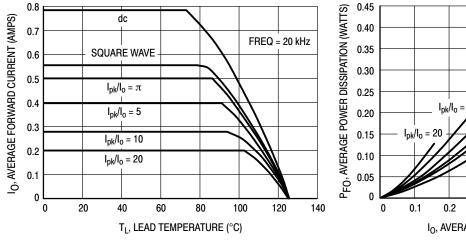


Figure 3. Typical Reverse Current

Figure 4. Maximum Reverse Current





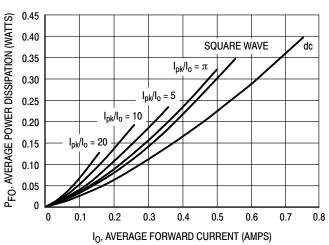


Figure 6. Forward Power Dissipation

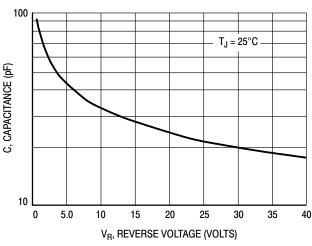


Figure 7. Capacitance

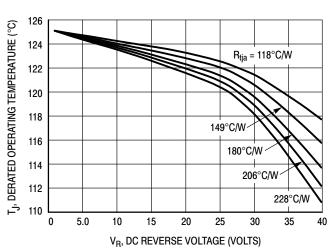


Figure 8. Typical Operating Temperature Derating*

r(t) = thermal impedance under given conditions,

Pf = forward power dissipation, and

Pr = reverse power dissipation

This graph displays the derated allowable T_J due to reverse bias under DC conditions only and is calculated as $T_J = T_{Jmax} - r(t)Pr$, where r(t) = Rthja. For other power applications further calculations must be performed.

^{*} Reverse power dissipation and the possibility of thermal runaway must be considered when operating this device under any reverse voltage conditions. Calculations of T_J therefore must include forward and reverse power effects. The allowable operating $T_J = T_{Jmax} - r(t)(Pf + Pr)$ where T_J may be calculated from the equation:

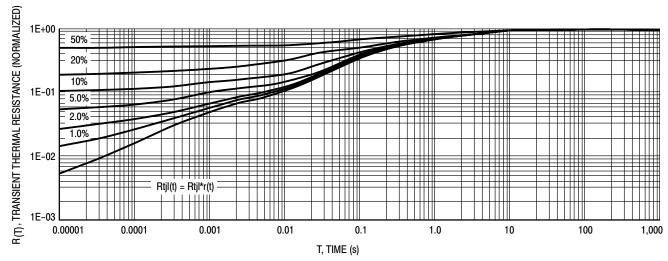


Figure 9. Thermal Response Junction to Lead

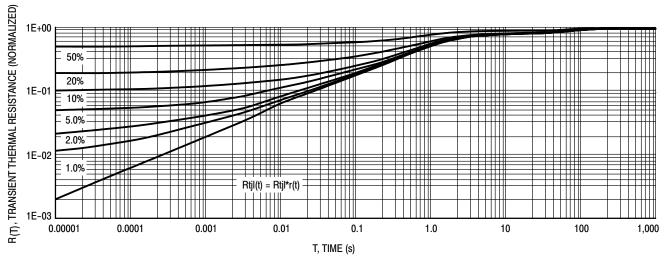
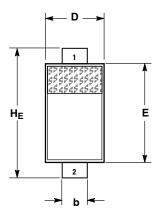
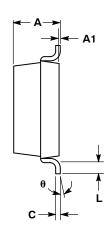


Figure 10. Thermal Response Junction to Ambient

PACKAGE DIMENSIONS

SOD-123 CASE 425-04 ISSUE G





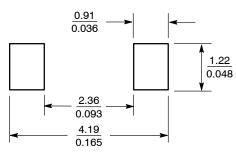
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI

 - Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.94	1.17	1.35	0.037	0.046	0.053	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
b	0.51	0.61	0.71	0.020	0.024	0.028	
С			0.15			0.006	
D	1.40	1.60	1.80	0.055	0.063	0.071	
E	2.54	2.69	2.84	0.100	0.106	0.112	
HE	3.56	3.68	3.86	0.140	0.145	0.152	
L	0.25			0.010			
θ	0°		10°	0°		10°	

STYLE 1: PIN 1. CATHODE 2 ANODE

SOLDERING FOOTPRINT*



 $\left(\frac{\text{mm}}{\text{inches}}\right)$ SCALE 10:1

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and III) are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights or the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to the surgical implant into the body, or other applications. intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT: Literature Distribution Center for ON Semiconductor

Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada

Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 Japan Customer Focus Center

Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

ON Semiconductor: